

**IN THE CLAIMS**

Please amend the claims to read as follows:

1 **Claim 1 (currently amended): A method of marking an electronic integrated circuit chip**  
2 **having surfaces comprising the following steps:**

3 **forming visible internal marking indicia on a marking location upon an exterior surface**  
4 **of the chip for identification of the chip, and**

5 **forming an optically transmissive encapsulating material over at least the marking**  
6 **location on the one exterior surface of the chip which optically transmissive material cannot**  
7 **be scraped off of the chip for prevention of replacement of the visible internal marking indicia**  
8 **by different markings.**

1 **Claim 2 (previously presented): The method of claim 1 wherein the optically transmissive**  
2 **material comprises a transparent or semi-transparent material.**

1 **Claim 3 (currently amended): The method of claim 1 wherein the optically transmissive**  
2 **encapsulating material is a protective encapsulating material ~~adapted to provide~~ providing**  
3 **protection from damage as the result of environmental and handling factors.**

1 **Claim 4. (previously presented): The method of claim 2 including the steps of:**  
2 **directing electromagnetic radiation upon the internal marking indicia through the**  
3 **optically transmissive material and**  
4 **reading the internal marking indicia in response to images of the internal marking**  
5 **indicia provided by reflections of the electromagnetic radiation.**

1 **Claim 5 (previously presented): The method of claim 1 wherein the optically transmissive**  
2 **material comprises a colored material.**

1 **Claim 6 (currently amended): The method of claim 1 wherein the optically transmissive**  
2 **material comprises [[a]] an epoxy material ~~such as epoxy~~ which prevents remarking indicia or**  
3 **identification marks on the chip.**

1 **Claim 7 (previously presented):** The method of claim 1 wherein the optically transmissive  
2 **material prevents remarking silicon for a semiconductor package and the optically**  
3 **transmissive material is a transparent material.**

1 **Claim 8 (previously presented):** The method of claim 7 including the steps of:  
2 **directing electromagnetic radiation upon the internal marking indicia through**  
3 **the optically transmissive material, and**  
4 **reading the internal marking indicia in response to images of the internal marking**  
5 **indicia provided by reflections of the electromagnetic radiation.**

1 **Claim 9 (currently amended):** A method of marking an electronic integrated circuit chip  
2 **having surfaces comprising the following steps:**

3 **forming a semiconductor, integrated circuit chip having surfaces including a planar**  
4 **front surface, a planar back surface and edges of the chip between the planar surfaces with at**  
5 **least one electrical contact site on a surface,**

6 **forming visible internal marking indicia upon an exterior marking portion of a surface**  
7 **of the chip for identification of the chip, and**

8 **forming a non-black layer covering the exterior surface of the chip at least at the exterior**  
9 **marking portion thereof, the non-black layer being composed, of a colored, optically**  
10 **transmissive material, which non-black layer cannot be scraped off of the chip for preventing**  
11 **replacement of the internal marking indicia by different markings and for preventing**  
12 **remarking the internal indicia on the exterior marking surface of the chip,**

13 **whereby the indicia are visible through the non-black layer.**

1 **Claim 10 (original):** The method of claim 9 including the steps of:

2 **directing electromagnetic radiation upon the internal marking indicia through**  
3 **the non-black optically transmissive material and**

4 **reading the internal marking indicia in response to images of the internal**  
5 **marking indicia provided by reflections of the electromagnetic radiation.**

Claim 11 canceled

1 Claim 12 (currently amended): A method of marking an electronic integrated circuit chip  
2 having surfaces comprising:

3 forming visible internal marking indicia on a marking location upon an exterior surface  
4 of the chip, and

5 forming a non-black, optically transparent material colored with a particular color over  
6 at least the marking location on that exterior surface of the chip wherein the material colored  
7 with the particular color together with the marking indicia represents identification of the chip  
8 which non-black, optically transparent, colored material cannot be scraped off of the chip for  
9 prevention of replacement of the internal marking indicia by different markings.

1 Claim 13 (currently amended): An electronic integrated circuit chip comprising:

2 the chip having exterior surfaces,

3 visible internal marking indicia formed on a marking location upon an exterior surface  
4 of the chip for identification of the chip, and

5 an optically transmissive material formed over at least the marking location on the one  
6 exterior surface of the chip which optically transmissive material cannot be easily scraped off  
7 for prevention of replacement of the internal marking indicia by different markings.

1 Claim 14 (previously presented): The chip of claim 13 wherein the optically transmissive  
2 material comprises a transparent or semi-transparent material.

1 Claim 15 (previously presented): The chip of claim 13 wherein the optically transmissive  
2 material comprises a colored material.

1 Claim 16 (previously presented): The chip of claim 13 wherein the optically transmissive  
2 material prevents remarking indicia or identification marks on the chip.

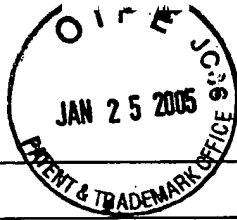
1 **Claim 17 (previously presented): The chip of claim 13 wherein the optically transmissive**  
2 **material prevents remarking silicon for a semiconductor package and the optically transmissive**  
3 **material is a transparent material.**

1 **Claim 18 (previously presented): The chip of claim 13 wherein:**  
2 **illumination means are provided for directing electromagnetic radiation upon the internal**  
3 **marking indicia through the optically transmissive material and**  
4 **reading means are provided for reading the internal marking indicia in response to images**  
5 **of the internal marking indicia provided by reflections of the electromagnetic radiation.**

1 **Claim 19 (previously presented): The chip of claim 13 wherein the optically transmissive**  
2 **material is providing protection from damage as the result of environmental and handling**  
3 **factors.**

1 **Claim 20 (previously presented): The chip of claim 14 wherein:**  
2 **illumination means are provided for directing electromagnetic radiation upon the internal**  
3 **marking indicia through the optically transmissive material and**  
4 **reading means are provided for reading the internal marking indicia in response to images**  
5 **of the internal marking indicia provided by reflections of the electromagnetic radiation.**

1 **Claim 21 (previously presented): The chip of claim 17 wherein:**  
2 **illumination means are provided for directing electromagnetic radiation upon the internal**  
3 **marking indicia through the optically transmissive material, and**  
4 **reading means are provided for reading the internal marking indicia in response to images**  
5 **of the internal marking indicia provided by reflections of the electromagnetic radiation.**



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1 22. (currently amended): An electronic integrated circuit chip comprising:  
2 a semiconductor, integrated circuit chip having surfaces including a planar front surface,  
3 a planar back surface and edges of the chip between the planar surfaces with at least one  
4 electrical contact site on a surface,

5 visible indicia marked upon an exterior marking portion of a surface of the chip for  
6 identification of the chip,

7 a cover layer covering the exterior surface of the chip at least at the exterior marking  
8 portion thereof, the cover layer being composed of a colored, optically transmissive material  
9 which optically transmissive material of the cover layer cannot be scraped off of the chip for  
10 prevention of replacement of the indicia by different markings and for preventing remarking  
11 the indicia on the exterior marking surface of the chip, and

12 the indicia being visible through the cover layer.

1 23. (previously presented): The chip of claim 22 wherein:

2 illumination means are provided for directing electromagnetic radiation upon the internal  
3 marking indicia through the optically transmissive material and

4 reading means are provided for reading the internal marking indicia in response to images  
5 of the internal marking indicia provided by reflections of the electromagnetic radiation.

24. Canceled

1 25. (currently amended): An electronic integrated circuit chip comprising:

2 internal marking indicia formed on a marking location upon an exterior surface of the  
3 chip, and

4 [[a]] an optically transparent material colored with a particular color formed over at least  
5 the marking location on that exterior surface of the chip wherein the material colored with the  
6 particular color together with the marking indicia represents identification of the chip, which  
7 optically transmissive material cannot be scraped off of the chip for prevention of replacement  
8 of the internal marking indicia by different markings.